

Questions?

What problem are we trying to solve?

Questions?

- What problem are we trying to solve?
- What's wrong with the current Eurocard system (I.e., 1101.1, .2, .10, .11)?

1101 Issues

- Cooling
- Power Distribution
- Dimensioning/Tolerances
- Cost
- Injector/Ejector -Forces
- Frontpanel - Shielding
- Too many screws

More 1101 Issues

- Board Area
- Pitch
- Backplane bow and stress
- IO - more pins!!!!
- IO Rear Guides
- Optical Interconnects
- Assembly Labor

Objective

- We want to develop a new modular system.
- What attributes should it have?
- What range of applications should it cover?

Dilemma

- One Size Fits All
- Multiple Profiles to address Multiple Apps.

What Forces Multiple Profiles?

- Size
- Performance
- Environment
- Could we eliminate enough of these to end up with only a few profiles that would cover most of the market.

IT

- Scalable Modular Architecture for the Embedded Marketplace
- Specific Markets
 - Comms
 - Military
 - Scientific/Industrial, etc.

IT continued

- Areas
 - Cooling
 - Mechanics
 - Board size
 - Guides, connectors, etc.
 - Power Dist
 - Protocol/SW Interoperability